

Title (en)  
COMPOSITION FOR PRETREATMENT FOR ELECTROLESS PLATING, PRETREATMENT METHOD FOR ELECTROLESS PLATING, AND ELECTROLESS PLATING METHOD

Title (de)  
ZUSAMMENSETZUNG ZUR VORBEHANDLUNG FÜR STROMLOSES PLATTIEREN, VORBEHANDLUNGSVERFAHREN FÜR STROMLOSES PLATTIEREN UND STROMLOSES PLATTIERUNGSVERFAHREN

Title (fr)  
COMPOSITION DE PRÉTRAITEMENT POUR DÉPOSITION AUTOCATALYTIQUE, PROCÉDÉ DE PRÉTRAITEMENT POUR DÉPOSITION AUTOCATALYTIQUE, ET PROCÉDÉ DE DÉPOSITION AUTOCATALYTIQUE

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Abstract (en)  
The present invention provides a pretreatment composition for electroless plating, a pretreatment method, and an electroless plating method that exhibit high plating deposition performance without using harmful chromic acid and expensive palladium, while reducing the number of steps. The present invention provides a pretreatment composition for electroless plating that contains 10 mg/L or more of manganese ions and 10 mg/L or more of monovalent silver ions.

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